

JEDEC PUBLICATION

PartModel Generated ECAD Models - Guidelines for Electronic-Device Packages – XML Requirements

JEP30-M100A

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JEDEC SOLID STATE TECHNOLOGY ASSOCIATION



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PartModel Generated ECAD Models Guidelines for Electronic-Device Packages – XML Requirements

(From JEDEC Board Ballots JCB-24-53 and JCB-25-59, formulated under the cognizance of the JC-11 Committee on Mechanical Standardization.)

1 Scope

The JEP30 document establishes the requirements for exchanging part data between part manufacturers and their customers for electrical and electronic products. The JEP30 documents are part of a series to describe XML data exchange structure and hierarchy. The JEP30 document series will detail data exchange between companies for design at the next level, analysis, and interconnection. The parent JEP30 document specifically focuses on the parental structure, under which several sub-sections are listed, such as electrical, physical, thermal, supply chain, assembly process classification, design kit, generated ECAD models, product substrate and assemblies, and environment including material declaration. This document specifically focuses on the GeneratedECAD-Models sub-section of the PartModel.

All releases of the [GeneratedECAD-Models](#) sub-schema must be under the umbrella of the PartModel Schema to ensure that the PartModel schema is referencing the correct version of the [GeneratedECAD-Models](#) sub-schema. In addition, this will enable the [GeneratedECAD-Models](#) sub-schema to connect to the Manufacturer Part Number and the Manufacturer of the Part.

1.1 Purpose

This standard is intended to benefit part manufacturers, ecad model generators and their customers by providing consistency and efficiency to the transfer of standardized ECAD models from model generators to customers. It establishes standard electronic data exchange formats that will facilitate and improve data transfer along the entire global supply chain, at every stage in the product life cycle. A key aspect therefore is the structure of the content that is contained in this format, which the committee believes should be based on the following two principles:

- 1) Data that is required to be consumed by software tools, and
- 2) Data that is not required to be consumed by software tools but is provided for informational purposes.

This standard specifically covers data applicable to the [GeneratedECAD-Models](#) that is required to support the design, fabrication and consumption modelling of the device.

2 Applicable Documents

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

2.1 JEDEC (www.jedec.org)

JEP30, *PartModel Guidelines for Electronic-Device Packages – XML Requirements*

JEP30-A100, PartModel Assembly Process Classification Guidelines for Electronic-Device Packages – XML Requirements

JEP30-E100, *PartModel Electrical Guidelines for Electronic-Device Packages – XML Requirements*

JEP30-P100, PartModel Package Guidelines for Electronic-Device Packages – XML Requirements

JEP30-T100, PartModel Thermal Guidelines for Electronic-Device Packages – XML Requirements

2.1.1 JEDEC PartModel Schema and Sub-Schemas

JEP30-10, PartModel Schema

JEP30-A101, PartModel Assembly Process Classification Schema

JEP30-E101, PartModel Electrical Schema

JEP30-P101, PartModel Package Schema

JEP30-S101, PartModel Supply Chain Schema

JEP30-T101, PartModel Thermal Schema

JEP30-K101, PartModel Design Kit Schema

JEP30-M101, PartModel Generated ECAD – Models Schema

JEP30-D10, *PartModel Schema Types Dictionary* (Required to support the PartModel Schema and each of its sectional sub-schemas.)

3 Requirements

The following terms and definitions are applicable to this XML Schema.

3.1 Terms and Definitions

All definitions and terms associated with the generated ECAD Model data are defined in the relevant standards that govern the definition of those parameters, as listed in the applicable documents section. The generated ECAD Model details of the part are defined in the [GeneratedECAD-ModelsSection](#) of the XML Schema.

All common Terms and Definitions that are used by more than one sectional sub-schema, such as any of the Assembly Process Classification, Electrical, Environmental, Package, Supply Chain, Thermal, Design Kits, or Generated ECAD Models are defined in the “JEP30-D10 PartModel Schema Types Library”.

All other definitions and terms necessary to define the schema, are defined by this document.

PartModel: A PartModel is a data representation described in an XML file that conforms to the rules and structure of the PartModel XML Schema.

NOTE 1 Companies who use the PartModel XML Files and claim compliance to JEDEC, must ensure that their PartModel XML file conforms to the specific released version of the PartModel XML Schema released by JEDEC.

NOTE 2 Section 4 will define the outline of the structure of the Generated ECAD Models XML Schema. Specific components of the XML Schema and their hierarchy are specifically controlled by the JC-11 Standards Committee who retain the expertise for these structures.

NOTE 3 The [GeneratedECAD-ModelsSection](#) of the schema forms part of the PartModel XML Schema and is not intended to act as a standalone schema. In addition, there is a “PartModel Schema Types Library” XML Schema, which is a common set of xml structures shared across the PartModel XML Schema and all of its sub-section schemas.

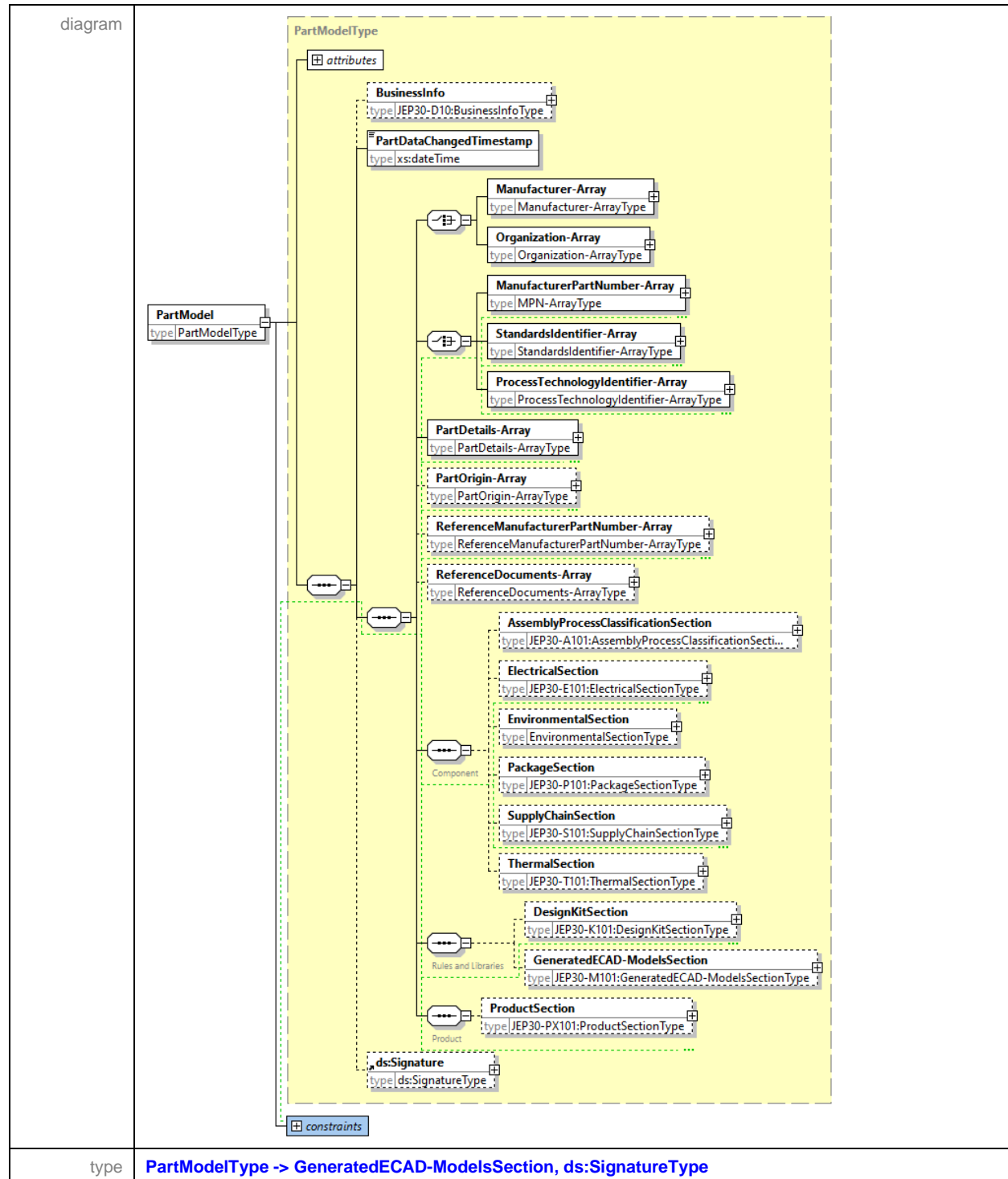
3.2 XML Schema Key Terms and Definitions

Reference the JEP30 publication for details of the "XML Schema Key Terms and Definitions".

4 PartModel Schema Definition

The following section describes the XML Schema structure.

4.1 PartModel – Generated ECAD - Models Section



4.1 PartModel – Generated ECAD - Models Section (cont'd)

The [PartModelType](#) belongs to the “PartModel XML Schema”. The [GeneratedECAD-ModelsSection](#) belongs to the “PartModel Generated ECAD Models XML Schema”. The primary purpose of the PartModel Schema is to provide the structure for identifying unique parts (Manufacturer and MPN) or unique standards (Organization and Standards Identifier) and the structure to include the sub schemas which define the part details, as outline in the JEP30 - PartModel Guidelines for Electronic-Device Packages – XML Requirements.

This document covers the [GeneratedECAD-ModelsSection](#), which is referenced from its parent’s structure, the [PartModel](#). The contents under the [GeneratedECAD-ModelsSection](#) are

1. Tied to the Manufacturer’s name and Manufacturer’s part number if the ECAD model is applicable to a part or a chiplet, or
2. Tied to a Standards Body and a Standards Model Identifier, if the ECAD models represents a standard set of Interfaces or Functions or Package Models as defined by a specific Standards Body.

All releases of the [GeneratedECAD-ModelsSection](#) sub-schema must be under the umbrella of the PartModel Schema to ensure that the PartModel schema is referencing the correct version of the Generated ECAD Models sub-schema. In addition, this will enable the Generated ECAD Models sub-schemas to connect to the identity structure as defined in the parent schema JEP30.

The [ComplianceToJEP30-M101SchemaVersion](#) indicates the version of the Schema to which the XML file is to be validated against. All new releases to this document or XML Schema is governed by the rules outlined in JEP30, and must be released in sync with the PartModel.

“Each time that a Sub-schema gets updated, then the PartModel version also gets updated in order to release that Sub-schema under the umbrella of the PartModel. This is because the PartModel must now reference the new version of sub-schema, since all subschemas have their own version number. The parent schema includes them by referring to a precise version, so a version bump in the subschema requires a version bump in the parent only at the time of release of the Parent.”

The [ECAD-ModelContentRevision](#) indicates the revision of the data for the Part that is submitted in the XML file. This enables the Component Manufacturer or the PartModel generator to provide a new XML file for a Part each time they wish to upgrade a new set of data for a part, in this [GeneratedECAD-ModelsSection](#).

The [PartModelECAD-ModelSectionStatus](#) attribute is a mandatory attribute that determines the status of the PartModel XML file. It has enumerated values of [Pre-Release](#), [Released](#), [Superseded](#), and [Withdrawn](#).

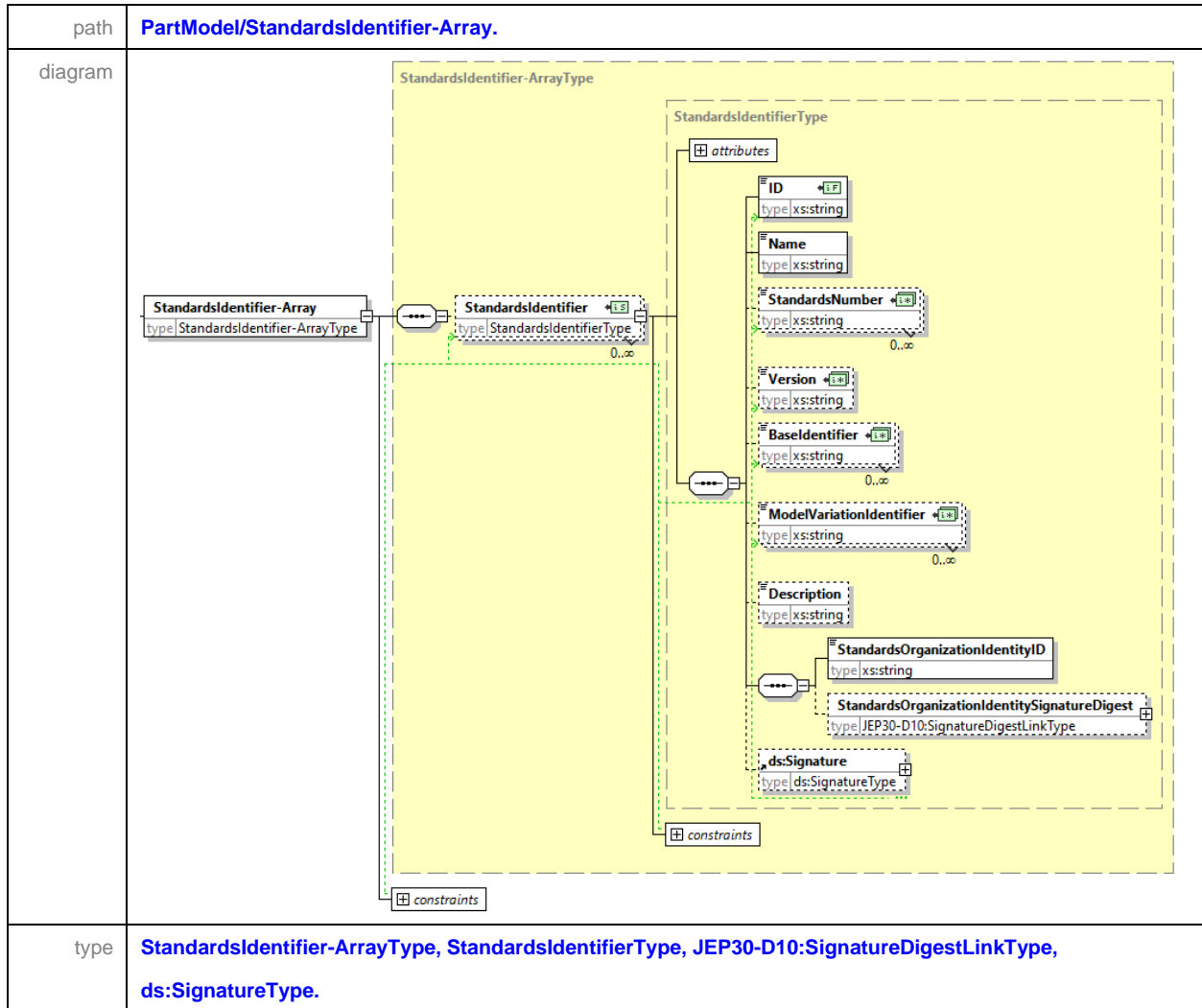
The [DocumentID](#) attribute provides a unique ID for the JEP30-P101 document that is being published.

4.2 Manufacturer Part Number-Array

path	PartModel/ManufacturerPartNumber-Array.
diagram	<p>The diagram illustrates the XSD structure for the ManufacturerPartNumber-Array. It is an array of ManufacturerPartNumbers (type MPN-ArrayType). Each ManufacturerPartNumbers element contains the following attributes and elements:</p> <ul style="list-style-type: none"> ID (type xs:string) PartNumberSeries (type JEP30-D10:PartNumberSeriesType) OrderablePartNumber (type JEP30-D10:OrderablePartNumberType) FuturePart (type FuturePartType) ManufacturerID (type xs:string) ManufacturerSignatureDigest (type JEP30-D10:SignatureDigestLinkType) ds:Signature (type ds:SignatureType) <p>The diagram also shows a constraints section at the bottom.</p>
type	MPN-ArrayType, ManufacturerPartNumbersType, JEP30-D10:PartNumberType, JEP30-D10:OrderablePartNumberType, FuturePartType, JEP30-D10:SignatureDigestLinkType, ds:SignatureType.

The [ManufacturerPartNumber-Array/ManufacturerPartNumbers](#) provides the definition of the part number, so that it can be connected to the technical specification details in the [GeneratedECAD-ModelsSection](#) via the [PartDetails-Array](#) section.

4.3 Standards Identifier - Array



The [StandardsIdentifier-Array/StandardsIdentifier](#) provides the definition of a specific Standard, so that it can be connected to the technical specification details in the [GeneratedECAD-ModelsSection](#) via the [PartDetails-Array](#) section.

4.4 Linking the Manufacturing Part Number to a specific ECAD Model Data set

The linking of the Parts, or Standards to its technical data is done via the [PartDetails-Array](#) section as outline in the JEP30 - PartModel Guidelines for Electronic-Device Packages – XML Requirements. This consists of two sections called [PartsSelection-Array](#) and [Association-Array](#) which defines the relationship between identifying the specific set of parts, standard interfaces, functions or packages and how they are associated with the ECAD Model content. Reference the JEP30 parent document for more details on this association.

path	PartModel/PartDetails-Array/PartDetails/Association-Array/Association/GeneratedECAD-Models-Array
diagram at the Association level	
type	GeneratedECAD-ModelsAssociation-ArrayType , FootprintAssociationType , SymbolAssociationType , TerminalName-to-NumberMappingAssociationType .
path	PartModel/GeneratedECAD-ModelsSection
diagram at the Generated ECAD - Models Section level	
type	JEP30-M101:GeneratedECAD-ModelsSectionType , GeneratedFootprint-ArrayType , GeneratedSymbol-ArrayType , TerminalName-to-NumberMapping-ArrayType , GeneratedECAD-ModelOrigin-ArrayType .

4.4.1 Linking the Manufacturing Part Number to Footprint ECAD Model

path	PartModel/PartDetails-Array/PartDetails/Association-Array/Association/GeneratedECAD-Models-Array/Footprint
diagram at the Footprint Generated ECAD Models Association level	
type	FootprintAssociationType, JEP30-D10:SignatureDigestLinkType.
path	PartModel/GeneratedECAD-ModelsSection/Footprint-Array
diagram at the Footprint Generated ECAD Models level.	
type	GeneratedFootprint-ArrayType, GeneratedFootprintType, JEP30-D10:EmptyType, JEP30-D10:InterconnectTechnology-ArrayType, JEP30-D10:PadOrHole-ArrayType, JEP30-D10:ThermalRelief-ArrayType, JEP30-D10:AssemblyOutlineLayerType, JEP30-D10:ConductiveArea-ArrayType, JEP30-D10:PlacementOutlineType, JEP30-D10:Keep-inLayer-ArrayType, JEP30-D10:KeepoutRegion-ArrayType, JEP30-D10:SoldermaskLayer-ArrayType, JEP30-D10:PastemaskLayer-ArrayType, ModelOriginType, ds:SignatureType.

4.3.1. Linking the Manufacturing Part Number to Footprint ECAD Model (cont'd)

The [FootprintID](#) references the [Footprint/ID](#) under the GeneratedECAD-ModelsSection/Footprint-Array. This is enforced by the key named as [GeneratedFootprintModelKey](#) that is assigned to the [Footprint/ID](#) element, which is referenced by the [FootprintID](#) which has a KeyRef that refers to the [JEP30-M101:GeneratedFootprintModelKey](#).

4.4.2 Linking the Manufacturing Part Number to Symbol ECAD Model

path	PartModel/PartDetails-Array/PartDetails/Association-Array/Association/GeneratedECAD-Models-Array/Symbol
diagram at the Symbol Generated ECAD Models Association level	
type	SymbolAssociationType , JEP30-D10:SignatureDigestLinkType .
path	PartModel/GeneratedECAD-ModelsSection/Symbol-Array
diagram at the Symbol Generated ECAD Models level.	
type	GeneratedSymbol-ArrayType , GeneratedSymbolType , JEP30-D10:SymbolGraphics-ArrayType , ModelOriginType , ds:SignatureType .

The [SymbolID](#) references the [Symbol/ID](#) under the GeneratedECAD-ModelsSection/Symbol-Array. This is enforced by the key named as [GeneratedSymbolModelKey](#) that is assigned to the [Symbol/ID](#) element, which is referenced by the [SymbolID](#) which has a KeyRef that refers to the [JEP30-M101:GeneratedSymbolModelKey](#).

4.4.3 Linking the Manufacturing Part Number to Terminal Name-to-Number Mapping

path	PartModel/PartDetails-Array/PartDetails/Association-Array/Association/GeneratedECAD-Models-Array/TerminalName-to-NumberMapping
diagram at the Material Design Kit Association level	
type	TerminalName-to-NumberMappingAssociationType , JEP30-D10:SignatureDigestLinkType .
path	PartModel/GeneratedECAD-ModelsSection/TerminalName-to-NumberMapping-Array
diagram at the Material Design Kit level.	
type	TerminalName-to-NumberMapping-ArrayType , TerminalName-to-NumberMappingType , Map-ArrayType , ModelOriginType , ds:SignatureType .

The [TerminalName-to-NumberMappingID](#) references the [TerminalName-to-NumberMapping/ID](#) under the [GeneratedECAD-ModelsSection/TerminalName-to-NumberMappingID-Array](#). This is enforced by the key named as [GeneratedTerminalName-to-NumberMappingKey](#) that is assigned to the [TerminalName-to-NumberMapping/ID](#) element, which is referenced by the [TerminalName-to-NumberMappingID](#) which has a KeyRef that refers to the [JEP30-M101:GeneratedTerminalName-to-NumberMappingKey](#).

5 Generated ECAD – Models Section

path	PartModel/GeneratedECAD-ModelsSection
diagram	<p>The diagram illustrates the structure of the GeneratedECAD-ModelsSectionType. It is a container for four main sections: Footprint-Array, Symbol-Array, TerminalName-to-NumberMapping-Array, and GeneratedECAD-ModelOrigin-Array. Each section has a specific type: GeneratedFootprint-ArrayType, GeneratedSymbol-ArrayType, TerminalName-to-NumberMapping-ArrayType, and GeneratedECAD-ModelOrigin-ArrayType respectively. The main container also includes attributes and constraints sections. A separate box labeled GeneratedECAD-ModelsSection (type: GeneratedECAD-ModelsSectionType) is shown connected to the main container.</p>
type	JEP30-M101:GeneratedECAD-ModelsSectionType, GeneratedFootprint-ArrayType, GeneratedSymbol-ArrayType, TerminalName-to-NumberMapping-ArrayType, GeneratedECAD-ModelOrigin-ArrayType.

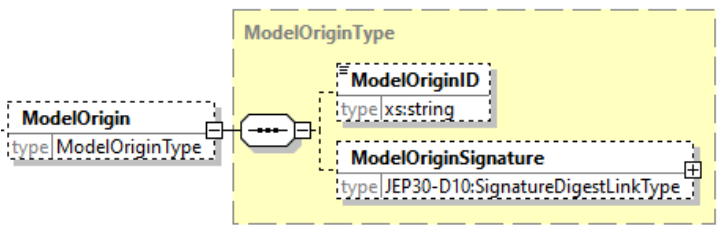
The **GeneratedECAD-ModelsSection** consists of 4 sections as shown above in the diagram. Each of these sections are described in further detail in the sub-sections below.

5.1 Footprint - Array

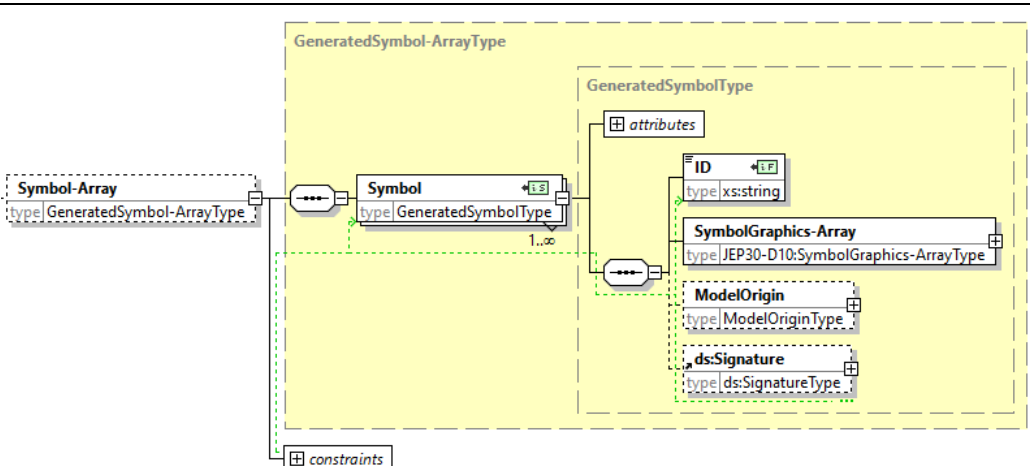
path	PartModel/GeneratedECAD-ModelsSection/Footprint-Array
diagram	
type	GeneratedFootprint-ArrayType, GeneratedFootprintType, JEP30-D10:EmptyType, JEP30-D10:InterconnectTechnology-ArrayType, JEP30-D10:PadOrHole-ArrayType, JEP30-D10:ThermalRelief-ArrayType, JEP30-D10:AssemblyOutlineLayerType, JEP30-D10:ConductiveArea-ArrayType, JEP30-D10:PlacementOutlineType, JEP30-D10:Keep-inLayer-ArrayType, JEP30-D10:KeepoutRegion-ArrayType, JEP30-D10:SoldermaskLayer-ArrayType, JEP30-D10:PastemaskLayer-ArrayType, ModelOriginType, ds:SignatureType.

The *Footprint-Array* follows the same structure as the Recommended Footprint Array that is specified in the JEP30-P100 PartModel Package Guidelines for Electronic-Device Packages – XML Requirements. Reference that document for the details of each sub-section.

5.1.1 Model Origin

path	PartModel/DesignKitSection/PackageAssemblyDesignKit-Array/PackageAssemblyDesignKit/RuleCondition-Array
diagram	 <p>The diagram shows a dashed box labeled ModelOrigin with the type <code>ModelOriginType</code>. This box is connected to a larger yellow box labeled ModelOriginType. Inside the yellow box, there are two sub-elements: ModelOriginID (type <code>xs:string</code>) and ModelOriginSignature (type <code>JEP30-D10:SignatureDigestLinkType</code>). The ModelOriginSignature element has a plus sign icon, indicating it is optional.</p>
type	ModelOriginType , JEP30-D10:SignatureDigestLinkType .

5.2 Symbol - Array

path	PartModel/GeneratedECAD-ModelsSection/Symbol-Array
diagram	 <p>The diagram shows a dashed box labeled Symbol-Array with the type <code>GeneratedSymbol-ArrayType</code>. This box is connected to a larger yellow box labeled GeneratedSymbol-ArrayType. Inside the yellow box, there are several sub-elements: constraints (indicated by a plus sign icon), Symbol (type <code>GeneratedSymbolType</code>, with a cardinality of 1..∞), and GeneratedSymbolType (indicated by a plus sign icon). The GeneratedSymbolType box contains: attributes (indicated by a plus sign icon), ID (type <code>xs:string</code>, with a cardinality of 1..1), SymbolGraphics-Array (type <code>JEP30-D10:SymbolGraphics-ArrayType</code>, with a plus sign icon), ModelOrigin (type <code>ModelOriginType</code>, with a plus sign icon), and ds:Signature (type <code>ds:SignatureType</code>, with a plus sign icon). The Symbol element is connected to the GeneratedSymbolType box via a line with a cardinality of 1..∞.</p>
type	GeneratedSymbol-ArrayType , GeneratedSymbolType , JEP30-D10:SymbolGraphics-ArrayType , ModelOriginType , ds:SignatureType .

The [Symbol-Array](#) follows the same structure as the Symbol-Array that is specified in the JEP30-E100 PartModel Electrical Guidelines for Electronic-Device Packages – XML Requirements. Reference that document for the details of each sub-section.

5.3 Terminal Name – to – Number Mapping - Array

path	PartModel/GeneratedECAD-ModelsSection/TerminalName-to-NumberMapping-Array
diagram	
type	TerminalName-to-NumberMapping-ArrayType , TerminalName-to-NumberMappingType , Map-ArrayType , ModelOriginType , ds:SignatureType .

5.3.1 Map - Array

path	PartModel/DesignKitSection/PackageAssemblyDesignKit-Array/PackageAssemblyDesignKit/DesignClassification-Array
diagram	
type	Map-ArrayType , MapType .

5.4 Generated ECAD - Model Origin - Array

path	PartModel/GeneratedECAD-ModelsSection/GeneratedECAD-ModelOrigin-Array
diagram	<p>GeneratedECAD-ModelOriginType</p> <p>attributes</p> <p>ID type xs:string</p> <p>DateTimestamp type xs:dateTime</p> <p>GeneratedECAD-ModelOriginDocumentID type xs:string</p> <p>Comment type xs:string</p> <p>OriginLocation-Array type JEP30-D10:OriginLocation-ArrayType</p> <p>Authorizer type JEP30-D10:ContactType</p> <p>Contact type JEP30-D10:ContactType</p> <p>ds:Signature type ds:SignatureType</p> <p>1..∞</p> <p>0..∞</p>
type	GeneratedECAD-ModelOrigin-ArrayType, GeneratedECAD-ModelOriginType, JEP30-D10:OriginLocation-ArrayType, JEP30-D10:ContactType, JEP30-D10:ContactType, ds:SignatureType, JEP30-D10:CompanyLocations-ArrayType

5.4.1 Origin Location - Array

path	PartModel/GeneratedECAD-ModelsSection/GeneratedECAD-ModelOrigin-Array/GeneratedECAD-ModelOrigin/OriginLocation-Array
diagram	<p>The diagram illustrates the XSD structure for the OriginLocation-Array. It is an array of OriginLocationType (1..∞). OriginLocationType is a choice between InternalCompanyLocationID and External. InternalCompanyLocationID is a choice between InternalCompanyLocationID (xs:string) and CompanyLocationSignatureDigest (SignatureDigestLinkType). External is a choice between ExternalOriginLocationType (1..2) and CompanyLocationSignatureDigest (SignatureDigestLinkType). ExternalOriginLocationType is a choice between ExternalCompanyLegalEntityLocationID (xs:string) and ExternalCompanyProcessOriginLocationID (xs:string).</p>
type	JEP30-D10:OriginLocation-ArrayType , OriginLocationType , ExternalOriginLocationType , SignatureDigestLinkType .

The [InternalCompanyLocationID](#), [ExternalCompanyLegalEntityLocationID](#), and the [ExternalCompanyProcessOriginLocationID](#) connect to the company location details under the [CompanyLocations-Array/CompanyLocation/ID](#).

It is recommended that the [GeneratedECAD-ModelOrigin](#) details contain the [Contact](#) and [Authorizer](#) details and that this structure is digitally signed off via the [GeneratedECAD-ModelOriginSignature](#). This will help to build trust in the supply chain for the part.

5.4.2 Company Location - Array

path	PartModel/GeneratedECAD-ModelsSection/GeneratedECAD-ModelOrigin-Array/CompanyLocations-Array
diagram	<p>The diagram illustrates the structure of the CompanyLocations-Array and its associated CompanyLocationType. The CompanyLocations-Array (type JEP30-D10:CompanyLocations-ArrayType) is an array containing CompanyLocation elements (type CompanyLocationType). The CompanyLocationType is a complex type with the following components:</p> <ul style="list-style-type: none">attributes: A container for attributes.ID: A required element (indicated by a solid line and a green box) of type xs:string.Name: A required element (indicated by a solid line and a green box) of type xs:string.SiteLocationIdentity: A required element (indicated by a solid line and a green box) of type SiteLocationIdentityType.Authorizer: An optional element (indicated by a dashed line and a green box) of type ContactType.Contact: An optional element (indicated by a dashed line and a green box) of type ContactType.ds:Signature: An optional element (indicated by a dashed line and a green box) of type ds:SignatureType. <p>The CompanyLocation element has a cardinality of 1..∞. The Authorizer and Contact elements have a cardinality of 0..∞. The ds:Signature element has a cardinality of 0..∞. A constraints container is also shown at the bottom of the CompanyLocationType structure.</p>
type	CompanyLocations-ArrayType, CompanyLocationType, SiteLocationIdentityType, JEP30-D10: ContactType, ds:SignatureType.

Annex A (informative) Differences between JEP30-M100 and its predecessors

This table briefly describes most of the changes made to entries that appear in this standard, JEP30-M100, compared to its predecessor; Punctuation changes may or may not be included.

Initial Issue:	Date: February 2025	Item Number: 11.2-1073
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Change Record History

Issue: A	Date: September 2025	Item Number: 11.2-1083
Description of Change		
Section 4.1 PartModel - SupplyChain Section: Updated images to match changes in the JEP30 parent schema		
Section 4.2 Manufacturer Part Number-Array: Updated images to match changes in the JEP30 parent schema		
Section 4.3 Standards Identifier Array: Added new section to connect Standards Identifiers to the Generated ECAD Models content.		
Changed signature element names to ds:Signature in all sections		



Standard Improvement Form**JEDEC Standard No. JEP30-M100A**

The purpose of this form is to provide the Technical Committees of JEDEC with input from the industry regarding usage of the subject standard. Individuals or companies are invited to submit comments to JEDEC. All comments will be collected and dispersed to the appropriate committee(s).

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1. I recommend changes to the following:

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☐ Test method number _____ Clause number _____

The referenced clause number has proven to be:

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☐ Other _____

2. Recommendations for correction:

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